



## Product Change Notification / ALAN-04KTCS710

### Date:

26-Oct-2022

### Product Category:

8-bit Microcontrollers

### PCN Type:

Manufacturing Change

### Notification Subject:

CCB 4764 Final Notice: Qualification of OSE as an additional assembly site for selected ATXMEGA128xx, ATXMEGA64xx, ATXMEGA32xx and ATXMEGA16xx device families available in 49L VFBGA (5x5x1.0mm) package.

### Affected CPNs:

[ALAN-04KTCS710\\_Affected\\_CPN\\_10262022.pdf](#)  
[ALAN-04KTCS710\\_Affected\\_CPN\\_10262022.csv](#)

### Notification Text:

**PCN Status:** Final notification

**PCN Type:** Manufacturing Change

**Microchip Parts Affected:** Please open one of the files found in the Affected CPNs section.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

**Description of Change:** Qualification of OSE as an additional assembly site for selected ATXMEGA128xx, ATXMEGA64xx, ATXMEGA32xx and ATXMEGA16xx device families available in 49L VFBGA (5x5x1.0mm) package.

### Pre and Post Change Summary:

	Pre Change	Post Change

Assembly Site		ASE Inc. (ASE)		ASE Inc. (ASE)	Orient Semiconductor Electronics, Ltd (OSE)
Substrate	Core Material	CCL-HL832NX (A-HS)		CCL-HL832NX (A-HS)	HL832NXA
	Process	Normal		Normal	Tenting
	L1/L2 Thickness	Min 12um		Min 12um	Copper 18+/-6 um, Ni 3um (min) Au 0.2um(min) OSP 0.3+/-0.15um"
	SM Material	AUS 308		AUS 308	AUS 320
Bond wire		CuPd		CuPd	CuPdAu
Die attach film (DAF)		ATB125		ATB125	EM-310WJ1-P-25
Mold compound		KE-G1250LKDS	KE-G1250LKDS		

**Impacts to Data Sheet:** None

**Change Impact:** None

**Reason for Change:** To improve manufacturability by qualifying OSE as an additional assembly site.

**Change Implementation Status:** In Progress

**Estimated First Ship Date:** November 30, 2022 (date code: 2249)

Note: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

#### Time Table Summary:

	October 2021					->	October 2022				November 2022			
	40	41	42	43	44		41	42	43	44	45	46	47	48
Workweek		X												
Initial PCN Issue Date														
Qual Report Availability									X					
Final PCN Issue Date									X					
Estimated Implementation Date														X

**Method to Identify Change:** Traceability code

**Qualification Report:** Please open the attachments included with this PCN labeled as PCN\_#\_Qual\_Report.

#### Revision History:

October 7, 2021: Issued initial notification.

**November 3, 2021:** Re-issuance of initial notification. Updated die attach film post change from HR-5104 to EM-310WJ1-P-25.

**October 26, 2022:** Issued final notification.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

## **Attachments:**

[PCN\\_ALAN-04KTCS710\\_Qual\\_Report.pdf](#)

Please contact your local **Microchip sales office** with questions or concerns regarding this notification.

## **Terms and Conditions:**

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